

1 SEMICONDUCTOR DEVICE WITH INDUCTIVE COMPONENT  
2 AND METHOD OF MAKING  
3

4 Abstract of the Disclosure  
5

6 An integrated circuit (10) includes a semiconductor  
7 substrate (11) that has a top surface (32) for forming a  
8 dielectric region (14) with a trench (40) and one or more  
9 adjacent cavities (16). A conductive material such as copper  
10 is disposed within the trench to produce an inductor (50). A  
11 top surface (49) of the inductor is substantially coplanar  
12 with an interconnect surface (31) of the semiconductor  
13 substrate, which facilitates connecting to the inductor with  
14 standard integrated circuit metallization (57).

09/920 222